

Sunright Corporate Press Release

SUNRIGHT ACQUIRES TESSERA'S FLEXIBLE CIRCUIT SUBSTRATE MANUFACTURING OPERATIONS IN SAN JOSE, CALIFORNIA

Singapore, May 4 2001 – Sunright, the world's largest independent burn-in and test service provider today announced the acquisition of Tessera's operations for the manufacturing of precision single and two metal layer flexible circuit substrates for advances semiconductor chip packaging. Tessera, Inc. is a provider of intellectual property for chip-scale packaging ("CSP"). The facility, located in San Jose, California, will be named, Flex2Chip, Inc. ("F2C"). As part of this acquisition, Sunright has acquired a license to Tessera's flexible circuit substrate technology.

The acquisition provides Sunright with synergistic technological capabilities, especially in the semiconductor service sector, where Sunright holds a leadership position. It complements Sunright's existing services by focusing on the "CSP" market, including burn-in and test. This further enhances Sunright's position as a global leader in the "burn-in and test" service technology.

Mr. Sam Lim, Sunright's Chairman and Chief Executive Officer explained, "the technology that Sunright is acquiring is widely used by leading semiconductor manufacturers and subcontract assemblers in the production of chip scale packages, which are growing rapidly in demand. CSPs are miniaturized, advanced semiconductor packages designed to enable the higher speeds and smaller sizes required for current and future cellular phones, laptop computers and a variety of other consumer applications".

Mr. Lim added, "the major trend toward miniaturization of electronic products drives the requirement for smaller internal components. For this reason, smaller form factor packages are becoming critically important, thereby increasing demand".

Electronic Trend Publications predicts that CSPs, the hottest market segment in IC packaging, will grow explosively from 885 million units in 1999 to 5,750 million units by 2003. This growth will be led by the 256-Mbit generation of dynamic random access memories ("DRAMs"), as the performance demands and size requirements for these devices will largely necessitate the use of CSPs. Other memory products, such as synchronous random access memories ("SRAMs") and Flash memories will also use CSPs heavily.

"The sale of the substrate manufacturing operations frees up valuable resources that will allow Tessera to better focus on its Intellectual Property ("IP") business model and more aggressively grow its service business," said Bruce McWilliams, President and CEO of Tessera. "The agreement with Sunright positions Tessera to remain at the forefront of packaging innovation while cutting costs and streamlining business operations".

Following this acquisition, Sunright plans to establish a mass production facility for the design and manufacture of advanced flex circuit substrates for chip scale packaging and other advanced packaging technologies. Flex2Chip will immediately

expand from being a captive flex circuit substrate manufacturer to offering its operations and technology license provides Sunright with a seamless entry into the flexible circuit marketplace and a solid foundation for establishing high-volume flexible circuit substrate manufacturing capabilities.”

Flexible Circuit Substrates

Flexible circuit-based packages make up a significant portion of the high growth of CSP market, and can be found in applications ranging from Flash Memory and DSPs for cell phones to high performance DRAM for powerful personal computers and video games. Flexible circuit substrates provide significant advantages over traditional rigid substrate materials. They are thinner and lighter than alternative materials – resulting in space savings for portable products – and provide enhanced heat transfer capabilities and improved electrical performance. Typical flexible substrate materials can endure higher temperatures and are less sensitive to moisture than rigid substrates, providing enhanced reliability and greater versatility.

About Tessera Inc.

Tessera provides intellectual property for chip-scale packaging to meet the accelerating demand for performance and miniaturization in wireless communications, Internet access, computing and consumer electronics products. Tessera’s technology enables the semiconductor industry to overcome fundamental problems in performance, reliability and size. Tessera currently licenses its advanced packaging technology to more than 30 assembly and semiconductor companies. Tessera is based in San Jose, Calif.

About Sunright

Sunright Limited, a main board listed company on the Singapore Exchange Securities Trading, is the world’s largest independent provider of burn-in and test services, and a leading manufacturer of parallel test and burn-in systems. Sunright also distributes high technology equipment and materials and engages in selective OEM assembly of electronic components. It has a total workforce of 2,500 employees with annual revenue in excess of S\$ 100 million. Sunright’s customers include multi-national semiconductor manufacturers, namely AMD, Hyundai, Hewlett-Packard, Infineon, Motorola, NEC, National Semiconductor, Texas Instruments, Toshiba and others. More information on Sunright is available on Sunright’s website: www.sunright.com.

Contact:

Sunright Limited
Yvonne Lim, (65) 3749546
yvonnelim@sunright.com